

List of Current Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1 - 29 (Cancelled).

30. (New) A circuit board having:
at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter; and
a holding mechanism in the form of a narrowing in said at least one connection bore to a diameter which is smaller than that of the connection wire, or pin for the purpose of providing a secure holding of the connection wire or pin.

31. (New) The circuit board as claimed in claim 30, wherein:
said narrowing is brought about by a foil.

32. (New) The circuit board as claimed in claim 31, wherein:
said foil narrowing the cross section of said connection bore is arranged on a surface of the circuit board.

33. (New) The circuit board as claimed in claim 31, wherein:
the circuit board is a multi-ply circuit board and that said foil narrowing the cross section of said connection bore is an inner ply of the circuit board.

34. (New) The circuit board as claimed in claim 31, wherein:
said foil is slit in the area of said connection bore.

35. (New) The circuit board as claimed in claim 31, wherein:
said foil is provided with a hole in the area of said connection bore.
36. (New) The circuit board as claimed in claim 31, wherein:
said foil comprises an electrically conductive material.
37. (New) The circuit board as claimed in claim 31, wherein:
said foil comprises an insulating, electrically non-conducting material.
38. (New) The circuit board as claimed in claim 30, wherein:
said narrowing is brought about by a unilateral bore, which is not completely
traversing.
39. (New) The circuit board as claimed in claim 30, wherein:
said narrowing is brought about by a beaker-shaped shell provided with a
restriction and situated in a traversing bore.
40. (New) The circuit board as claimed in claim 30, wherein:
said narrowing is brought about by two bores.
41. (New) The circuit board as claimed in claim 40, wherein:
said narrowing is brought about by two equally directed bores having different
diameters.
42. (New) The circuit board as claimed in claim 40, wherein:
said narrowing is brought about by two oppositely directed bores

43. (New) The circuit board as claimed in claim 42, wherein:

said narrowing is brought about by two oppositely directed bores, which are offset relative to one another.

44. (New) A method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

applying a foil onto a surface of the circuit board following manufacture of at least one ply, or layer, of the circuit board and drilling of the connection bore to cover the connection bore; and

opening the foil in the area of the connection bore in such a manner that a narrowing in cross section of a part of the connection bore is formed, wherein:

the narrowing is smaller than the wire, or pin, diameter of the electronic component and provides a holding mechanism for secure holding of the connection wire, or pin.

45. (New) The method as claimed in claim 44, wherein:

the foil is slit in the area of the connection bore.

46. (New) The method as claimed in claim 44, wherein:

the foil is provided with a hole in the area of the connection bore.

47. (New) The method as claimed in claim 44, wherein:

the foil is opened by means of a laser.

48. (New) The method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer; and
drilling the circuit board from a surface of the circuit board, with a drilling tool of a nominal diameter, in such a manner that the drilling tool does not completely pass through the circuit board and the connection bore therefore has in a region a cross section of diameter smaller than the wire, or pin, diameter of the electronic component, so that a narrowing brought-about thereby in the cross section of the connection bore forms a holding mechanism for secure holding of the connection wire, or pin.

49. (New) The method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;
completely drilling through the circuit board at a location desired for the connection bore; and

placing a breaker shaped insert into the connection bore, which has a restriction its cross section, the diameter of the restriction being smaller than the wire, or pin, diameter of the electronic component, the restriction representing a holding mechanism for secure holding of the connection wire, or pin.

50. (New) A method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;
drilling a blind hole with a drilling tool having a desired diameter, into the circuit board at a location desired for the connection bore; and

drilling through the floor of the blind hole with a drilling tool having a diameter smaller than the wire, or pin, diameter, in order to form a second bore, so that a narrowing created thereby in the cross section of a part of the connection bore forms a holding mechanism for secure holding of the connection wire, or pin.

51. (New) A method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;

drilling a first blind hole at a location desired for the connection bore, into the circuit board from a first surface of the circuit board with a drilling tool of a desired diameter; and

drilling a second blind hole from a second surface of the circuit board, into the circuit board, which is arranged slightly offset from the first blind hole and which meets the first blind hole, so that, by the offset of the two blind holes relative to one another, a restriction is formed, which represents a holding mechanism for secure holding of the connection wire, or pin.

52. (New) A method for manufacturing a circuit board having at least one connection bore for receiving a connection wire, or pin, of an electronic component of a predetermined wire, or pin, diameter, comprising the steps of:

manufacturing a circuit board with at least one ply, or layer;

drilling a first blind hole, at a location desired for the connection bore, into the circuit board from a first surface of the circuit board with a drilling tool of a desired diameter; and

drilling a second blind bore from a second surface of the circuit board, into the circuit board a second, which is arranged essentially axially parallel and aligned with the first blind hole and which meets the first blind hole but does not extend completely into it, so that, in a portion of the connection bore, where the two blind holes meet one another, a restriction is formed, which represents a holding mechanism for secure holding of the connection wire, or pin.

53. (New) The use of a circuit board as claimed in claim 30 with at least one electronic component held in the connection bore by means of the holding mechanism for soldering the component in a reflow soldering oven.

54. (New) The use of a circuit board as claimed in claim 53 for a soldering method, in which the component is soldered hanging below the circuit board in a reflow soldering oven.

55. (New) The use of a circuit board as claimed in claim 30, with at least one electronic component held in the connection bore by means of a holding mechanism for soldering the component in a wave soldering facility.

56. (New) The use of a circuit board manufactured according to a method as claimed in claim 44 and populated with at least one electronic component held in the connection bore by means of a holding mechanism for soldering the component in a reflow soldering oven.

57. (New) The use of a circuit board as claimed in claim 56 for a soldering method, in which the component is soldered hanging beneath the circuit board in the reflow soldering oven.

58. (New) The use of a circuit board manufactured according to a method as claimed in claim 44 and populated with at least one electronic component held in the connection bore by means of a holding mechanism for soldering the component in a wave soldering facility.